

ABSTRACT OF THE INVENTION

A dual-layer heat dissipating structure includes a first heat sink, a second heat sink, and a heat pipe with a connecting portion and a curved portion, interconnecting the first and second heat sinks for thermal conduction.

- 5 The first and second heat sinks each has a substrate and exterior fins protruding from two opposing ends thereof. Two substrates each includes at least one slot through out of two corresponding end plates of the same side for locating the connecting portion, and the corresponding end plates each includes an opening with respect to the slot for partially moving in the curved
- 10 portion. The exterior fins of the first and second heat sinks are aligned with each other, and a snap-type connecting structures are formed on terminuses of the exterior fins. The second and first heat sinks are connected to each other by the snap-type structure, and the connection joint is reinforced by implanting soldering material.

15